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L1 and adhesion near promoter and seed and substrate

#	Document ID	Issue Date	Pages	Title	Current OR	Current Xref
1	<input type="checkbox"/> US 20050092621 A1	20050505	13	Composite pad assembly for electrochemical mechanical processing (ECMP)	205/668	
2	<input type="checkbox"/> US 20050082676 A1	20050421	17	Silicon chip carrier with through-via using laser assisted chemical vapor deposition of conductor	257/763	
3	<input type="checkbox"/> US 20050023145 A1	20050303	100	Methods and apparatus for forming multi-layer structures using adhered masks	205/116	205/135
4	<input type="checkbox"/> US 20040214098 A1	20041029	6	Photoresist formulation for high aspect ratio plating	430/5	
5	<input type="checkbox"/> US 20040201095 A1	20041011	16	Through-via vertical interconnects, through-via heat sinks and associated fabrication methods	257/700	257/698; 257/E21.597; 257/E23.031
6	<input type="checkbox"/> US 20040175653 A1	20040909	22	Photosensitive composition and use thereof	430/280.1	430/284.1; 430/285.1; 430/287.1
7	<input type="checkbox"/> US 20040004001 A1	20040108	32	Method of and apparatus for forming three-dimensional structures integral with semiconductor-based carriers	205/116	205/134
8	<input type="checkbox"/> US 20030198802 A1	20031009	17	Method for forming a plug metal layer	438/672	257/E21.171; 257/E21.564
9	<input type="checkbox"/> US 20030138731 A1	20030724	7	Photoresist formulation for high aspect ratio plating	430/280.1	430/912; 430/954; 522/170
10	<input type="checkbox"/> US 20030124787 A1	20030703	17	Method for forming a plug metal layer	438/200	257/E21.171; 257/E21.564
11	<input type="checkbox"/> US 20030100190 A1	20030529	12	Process for forming a damascene structure	438/710	438/709